

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of **Rutten**

Serial No.:

Filed:

Title: **CHIP-MOUNTED CONTACT SPRINGS**

Atty. Docket No.: **US 018180**

Group Art Unit:

Examiner:



Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

Sir:

Enclosed is an Information Disclosure Citation and copies of documents listed thereon.

These documents are considered to be relevant in that they have been:

☒ considered in drafting the specification of the above-referenced application;

☒ cited in the specification of the above-referenced application; or,

☐ cited as an "X" or "Y" document in a foreign Patent Office search report on a foreign counterpart application, a copy of which report is also enclosed;

☐ I hereby certify that these documents were cited in said search report not more than three (3) months ago.

☐ Please charge any fee under 1.17(p) for this Information Disclosure Statement to be considered, not exceeding \$, to Deposit Account No. .

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Robert M. McDermott".

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CERTIFICATE OF MAILING

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On 8 Nov 01 By R M McDermott

INFORMATION DISCLOSURE CITATION
(37 CFR 1.97)

Application Number
Filing Date
First Named Inventor **Rutten**
Group Art Unit
Examiner Name
Attorney Docket **US 018180**

1036 U.S. PTO
10/005689
11/08/01

U.S. PATENT DOCUMENTS							
Examiner's Initials	Cite No.	Patent Number	Date	Name	Class	Sub-Class	Filing Date, If Approp.
	AA	6,075,373	13 June 2000	Iino			
	AB	6,169,410 B1	2 January 2001	Grace et al.			
	AC	(copending application) "PRECONDITIONED INTEGRATED CIRCUIT FOR INTEGRATED CIRCUIT TESTING"		Rutten			(concurrent)
	AD						
	AE						
	AF						
	AG						
	AH						

FOREIGN PATENT DOCUMENTS								
Examiner's Initials	Cite No.	Patent Number	Date	Country	Class	Sub-Class	Translation	
							Yes	No
	AI	EP 0 755 071 A2	18 July 1996	Europe				
	AJ							
	AK							
	AL							
	AM							

Examiner's Initials	Cite No.	Other (Include Author, Title, Date, Pertinent Pages, Etc.)
	AN	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg2.html
	AO	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg5.html
	AP	"Focus on FormFactor", THE FINAL TEST REPORT, Vol. 12, No. 09, September 2001, Ikonix Corp. P.O. Box 1938, Lafayette, CA 94549-1938
	AQ	"Flip-Chip Bonding on 6-um Pitch using Thin-Film Microspring Technology", Donald L. Smith et al., Xerox Palo Alto Research Center, Proceedings, 48 th Electronic Components and Technology Conference, IEEE, May 1998.
	AR	

Examiner	Date Considered
Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include a copy of this form with next communication to the Applicant.	